

ABSTRACT

The present invention provides a heat-curable resin composition having excellent fluidity and realizing moisture-resistance reliability suitable for recent electronic component-related materials and high flame retardancy in a halogen-free state for harmony with the environment, a cured product thereof, a semiconductor encapsulating material using the composition, and a phenol resin and epoxy resin which give these performances. The heat-curable resin composition includes, as essential components, an epoxy resin (A) and a phenol resin (B), the phenol resin (B) having a phenol resin structure having, as a basic skeleton, a structure in which a plurality of phenolic hydroxyl group-containing aromatic skeletons (ph) are bonded to each other through an alkylidene group or a methylene group having an aromatic hydrocarbon structure, and an aromatic nucleus of the phenol resin structure has a naphthylmethyl group or an anthrylmethyl group.